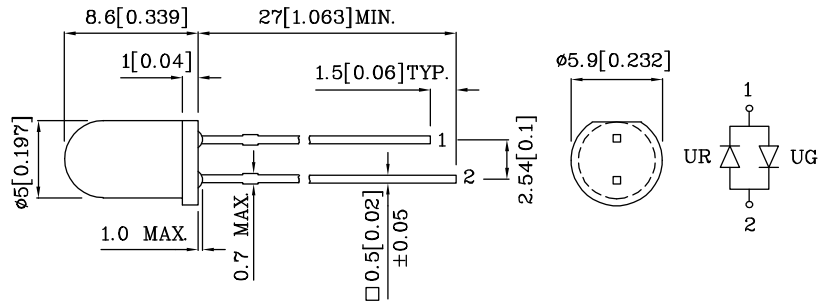


Features

- LOW POWER CONSUMPTION.
- I.C. COMPATIBLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.



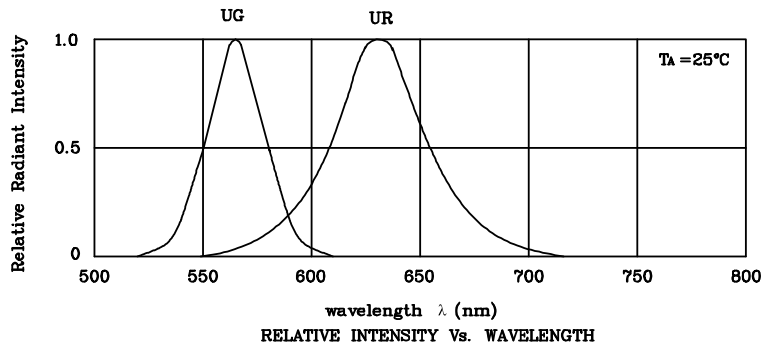
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

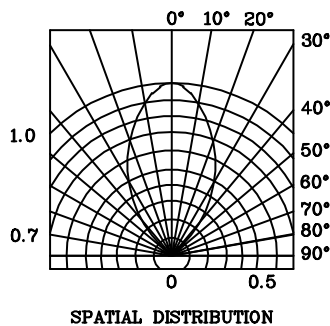
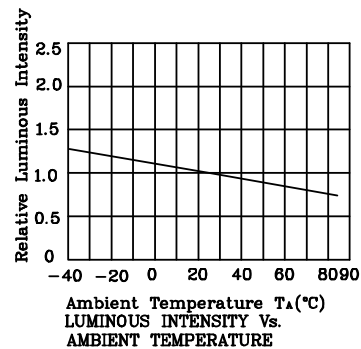
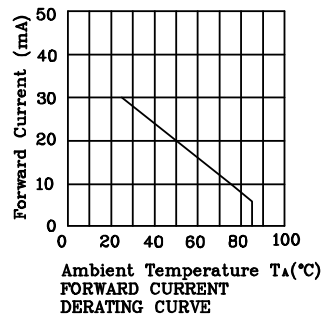
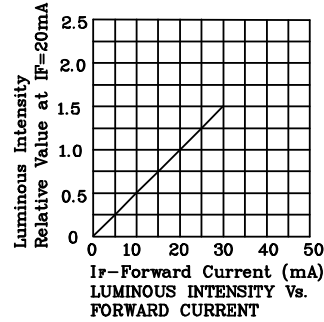
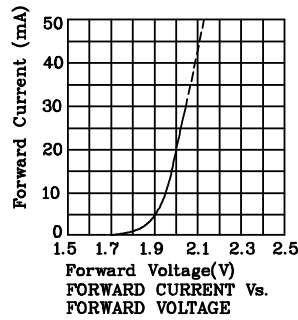
Absolute maximum ratings ($T_A=25^\circ\text{C}$)		UR (GaAsP/ GaP)	UG (GaP)	Unit
Forward Current	I_F	30	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	140	mA
Power Dissipation	P_T	105	105	mW
Operating Temperature	T_A	-40 ~ +85		°C
Storage Temperature	T_{stg}	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/ GaP)	UG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.0	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	2.5	V
Wavelength of Peak Emission ($I_F=20\text{mA}$)	λ_P	627	565	nm
Wavelength of Dominant Emission ($I_F=20\text{mA}$)	λ_D	625	568	nm
Spectral Line Full Width At Half-Maximum ($I_F=20\text{mA}$)	$\Delta\lambda$	45	30	nm
Capacitance ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	15	pF

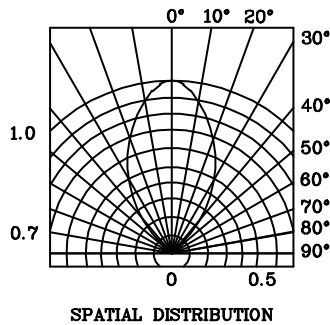
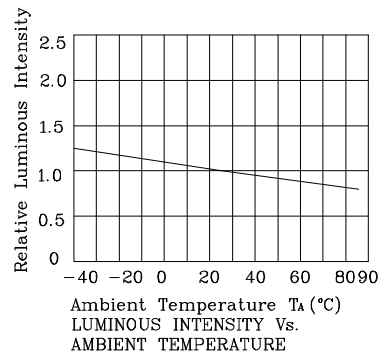
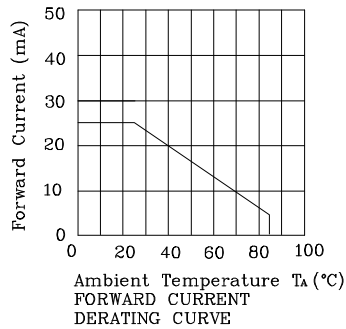
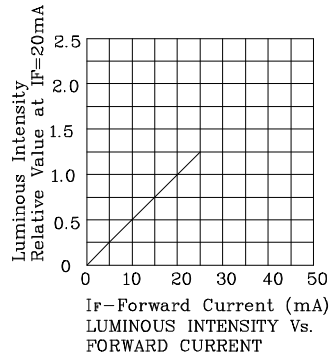
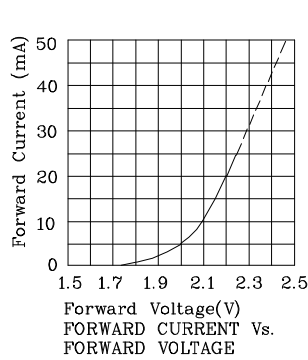
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle $2\theta_{1/2}$
				min.	typ.		
XLUGR58M	Red	GaAsP/GaP	White Diffused	10	29	627	60°
	Green	GaP		10	19	565	



❖ UR



❖ UG



Remarks:

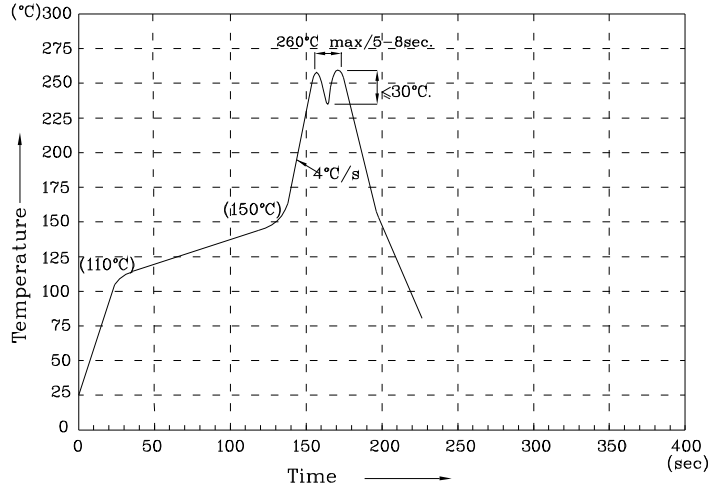
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XLUGR58M

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.